AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended): A compression bonding method comprising:

~~patterning~~ disposing a plurality of metal bonding film shapes in a pattern ~~predetermined shapes~~ on a substrate; and

disposing a bonded element above the plurality of metal bonding film shapes and applying heat to the substrate and pressure to the bonded element, thereby bonding the bonded element to the substrate having the plurality of metal bonding film shapes,

wherein the bonded element is plate shaped.

2. (currently amended): A compression bonding method comprising:

~~patterning~~ disposing a first plurality of metal bonding film shapes in a pattern ~~predetermined shapes~~ on a substrate and ~~patterning~~ disposing a second plurality of metal bonding film shapes in a pattern ~~the predetermined shapes~~ on a bonded element; and

disposing the bonded element above the first plurality of metal bonding film shapes and applying heat to the substrate and pressure to the bonded element, thereby bonding the bonded element having the second plurality of metal bonding ~~element~~ film shapes to the substrate having the first plurality of metal bonding ~~element~~film shapes,

wherein the first plurality of metal bonding film shapes are spaced apart from each other.

3. (currently amended): The compression bonding method of claim 1 ~~or 2~~, wherein the substrate is made of a material selected from the group consisting of silicon, metal, and ceramic.

4. (currently amended): The compression bonding method of claim 1 ~~or 2~~, wherein the metal bonding film is made of a material selected from the group consisting of aluminum, magnesium, zinc, and titanium.

5. (currently amended): The compression bonding method of claim 1 ~~or 2~~, wherein the ~~predetermined~~ plurality of metal bonding film shapes are stripes or dots.

6. (currently amended): The compression bonding method of claim 1 ~~or 2~~, wherein the bonded element is glass or metal.

7. (currently amended): The compression bonding method of claim 1 ~~or 2~~, wherein he heat is lower than 350°C.

8. (new): The compression bonding method of claim 1, wherein the bonded element contacts more than one of the plurality of metal bonding film shapes.

9. (new): The compression bonding method of claim 2, wherein the substrate is made of a material selected from the group consisting of silicon, metal, and ceramic.

10. (new): The compression bonding method of claim 2, wherein the first and second plurality of metal bonding film shapes are made of a material selected from the group consisting of aluminum, magnesium, zinc, and titanium.

11. (new): The compression bonding method of claim 2, wherein the first and second plurality of metal bonding film shapes are stripes or dots.

12. (new): The compression bonding method of claim 2, wherein the bonded element is glass or metal.

13. (currently amended): The compression bonding method of claim 2, wherein he heat is lower than 350°C.

14. (new): The compression bonding method claim 2, wherein the bonded element contacts more than one of the first and second plurality of metal bonding film shapes.